

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

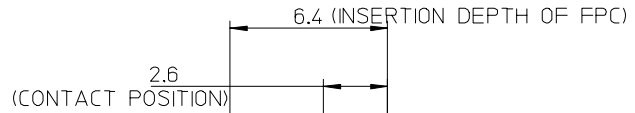
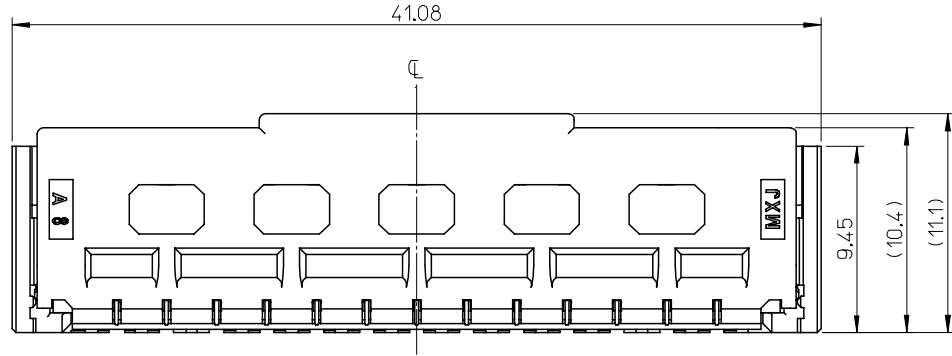
E

D

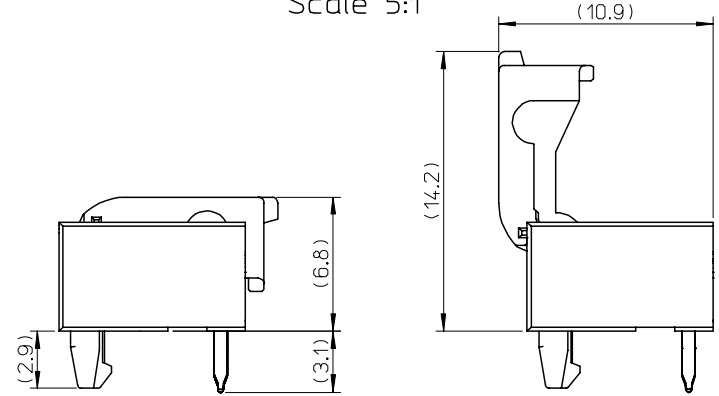
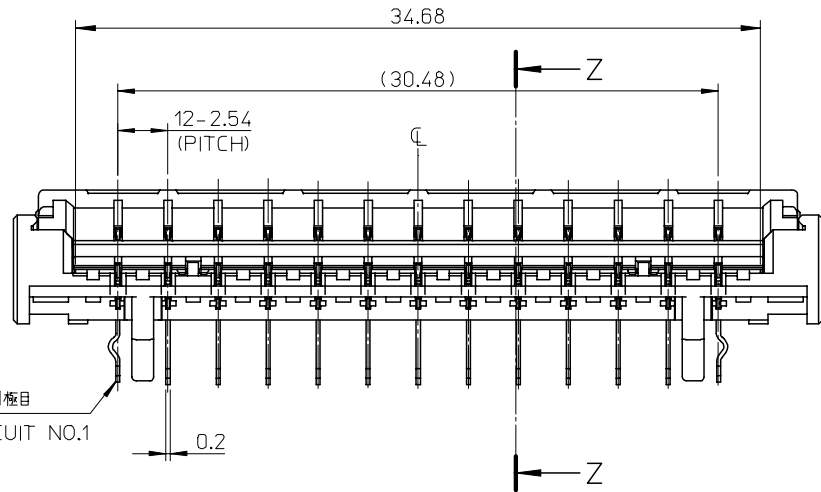
C

B

A



SECTION Z-Z  
Scale 5:1



アクチュエータ閉じている状態  
ACTUATOR CLOSED

アクチュエータ開いている状態  
ACTUATOR OPEN

RELEASED EC NO: J2007-3187 DRWN:KONURAKAMI 2007/05/23 CHKD:K.TAKAHASHI 2007/05/23 APPR:K.TAKAHASHI 2007/05/24	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY K.MURAKAMI	DATE 2007/05/22	TITLE 2.54MM FPC CONN EO BACK FLIP HSG ASS'Y			
	10 OVER 30 UNDER	±0.2	CHECKED BY K.TAKAHASHI	DATE 2007/05/22				
	30 OVER	±0.2	APPROVED BY H.HIRATA	DATE 2007/05/22	MOLEX INCORPORATED			
	ANGULAR	±1 °	MATERIAL NO. 502378-1310	DOCUMENT NO. SD-502378-001				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9

8

7

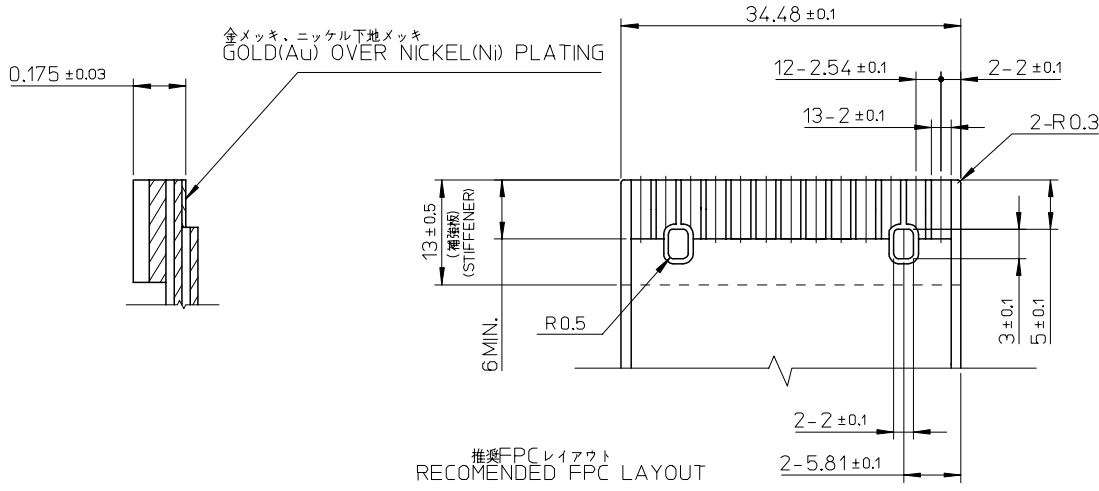
6

5

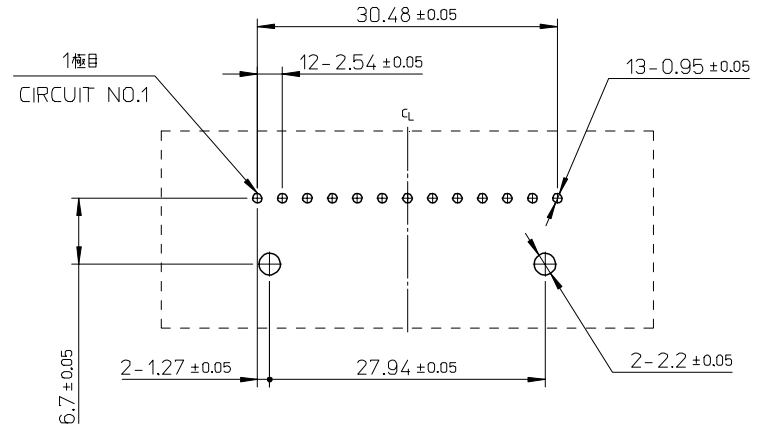
4

3

2



推奨FPCレイアウト  
RECOMMENDED FPC LAYOUT  
(仕上がり厚さ:0.175±0.03)  
(THICKNESS:0.175±0.03)



推奨基板レイアウト  
RECOMMENDED P.C.BOARD LAYOUT

注記 NOTES

- 1.使用材料 MATERIAL  
ハウジング:46ナイロン UL94 V-0  
HOUSING:PA46 UL94 V-0  
アクチュエータ:46ナイロン UL94 V-0  
ACTUATOR:PA46 UL94 V-0  
ターミナル:リン青銅  
TERMINAL: PHOSPHOR BRONZE
- 2.メッキ仕様 PLATING  
コンタクト部:金メッキ(0.1マイクロメートル以上 封孔処理)  
CONTACT AREA:GOLD PLATING  
(0.1 MICROMETER MIN.FOR SEALING DEPOSITION)  
半田付け部:錫メッキ  
SOLDERING AREA:TIN PLATING  
下地:ニッケルメッキ  
UNDER PLATING:NICKEL PLATING
- 3.ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT.

FPCについて:

打抜き方向は導体側から補強板側を推奨致します。  
導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを推奨致します。  
ABOUT FPC  
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
RECOMMENDED CONDUCTOR SPEC :  
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER  
補強フィルム材質はポリイミドを推奨致します。  
接着剤は熱硬化接着剤を推奨致します。  
ベースフィルムは25マイクロメートルを推奨致します。  
RECOMMENDED MATERIAL :  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT  
RECOMMENDED THICKNESS :  
BASE FILM : 25 MICROMETER

RELEASED EC NO: J2007-3187 DRW:KONURAKAMI 2007/05/23 CHK:K.TAKAHASHI 2007/05/23 APPR:K.TAKAHASHI 2007/05/24 REV A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY K.MURAKAMI		DATE 2007/05/22	TITLE 2.54MM FPC CONN EO BACK FLIP HSG ASS'Y		
	10 OVER 30 UNDER	±0.2	CHECKED BY K.TAKAHASHI		DATE 2007/05/22	MOLEX INCORPORATED		
	30 OVER	±0.2	APPROVED BY H.HIRATA		DATE 2007/05/22	DOCUMENT NO. SD-502378-001		
ANGULAR ±1		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. 502378-1310	SHEET NO. 2 OF 2			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								